

**Detail specification: Fixed low power  
film SMD resistors - Cylindrical -  
Stability classes 0,05; 0,1; 0,25; 0,5; 1; 2**

Detail specification: Fixed low power film SMD  
resistors - Cylindrical - Stability classes 0,05; 0,1;  
0,25; 0,5; 1; 2

## EESTI STANDARDI EESSÕNA

## NATIONAL FOREWORD

<p>Käesolev Eesti standard EVS-EN 140401-803:2007 sisaldab Euroopa standardi EN 140401-803:2007 ingliskeelset teksti.</p> <p>Käesolev dokument on jõustatud 23.11.2007 ja selle kohta on avaldatud teade Eesti standardiorganisatsiooni ametlikus väljaandes.</p> <p>Standard on kättesaadav Eesti standardiorganisatsioonist.</p>	<p>This Estonian standard EVS-EN 140401-803:2007 consists of the English text of the European standard EN 140401-803:2007.</p> <p>This document is endorsed on 23.11.2007 with the notification being published in the official publication of the Estonian national standardisation organisation.</p> <p>The standard is available from Estonian standardisation organisation.</p>
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<p><b>Käsitlusala:</b> Fixed low power non wire-wound surface mount resistors (SMD) cylindrical style: RC. Electronic components of assessed quality in accordance with EN 60115:201; EN 140400:200X; EN 140401:2002</p>	<p><b>Scope:</b> Fixed low power non wire-wound surface mount resistors (SMD) cylindrical style: RC. Electronic components of assessed quality in accordance with EN 60115:201; EN 140400:200X; EN 140401:2002</p>
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**ICS** 31.040.10

**Võtmesõnad:** cylindrical shape, detail specification, electronic equ, electronic equipment and components, fixed resistors, non-wire-wound, resistors, smd, specification, stability, surface mounting

English version

**Detail specification:  
Fixed low power film SMD resistors -  
Cylindrical -  
Stability classes 0,05; 0,1; 0,25; 0,5; 1; 2**

Spécification particulière:  
Résistances couche fixes  
à faible dissipation CMS -  
Cylindriques -  
Catégories de stabilité  
0,05; 0,1; 0,25; 0,5; 1; 2

Bauartspezifikation:  
SMD Schicht-Festwiderstände  
niedriger Belastbarkeit -  
Zylindrisch -  
Stabilitätsklassen 0,05; 0,1; 0,25; 0,5; 1; 2

This European Standard was approved by CENELEC on 2007-05-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

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**CENELEC**

European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

**Central Secretariat: rue de Stassart 35, B - 1050 Brussels**

## Foreword

This European Standard was prepared by the Technical Committee CENELEC TC 40XB, Resistors.

The text of the draft was submitted to the Unique Acceptance Procedure and was approved by CENELEC as EN 140401-803 on 2007-05-01.

This European Standard supersedes EN 140401-803:2002 + A1:2003.

Preceding documents on the subject covered by this specification have been

- CECC 40 401-803:1997,  
only on resistors without established reliability, now version A:
- CECC 40 401-005:1990; 1991; 1992,  
only on resistors with established reliability, now version E:
- CECC 40 401-001:1988; 1990.

Compared to the superseded standard, the following changes have been implemented:

- modification of the title;
- introduction of a test on the resistance to electrostatic discharge in 1.6 and Annex A;
- introduction of description and test methods for lead-free soldering in 1.8, 1.10.3 and Annex A;
- introduction of the code letters for temperature coefficient as given in EN 60062;
- revision of the ordering information in 1.9.4;
- revised information on pulse load capability in 1.10.6;
- revised information on resistance value drift in 1.10.7;
- revised information on current noise in 1.10.9;
- adoption of the IECQ rules of procedure, QC 001002-3;
- revision of the sample quantities and the sequence of tests in Annex A;
- editorial revision.

The following dates were fixed:

- latest date by which the EN has to be implemented  
at national level by publication of an identical  
national standard or by endorsement (dop) 2008-05-01
- latest date by which the national standards conflicting  
with the EN have to be withdrawn (dow) 2010-05-01

This specification is part of four documents describing fixed resistors for surface mount technology as follows:

EN 60115-1	Fixed resistors for use in electronic equipment - Part 1: Generic specification (IEC 60115-1, mod.)
EN 140400	Sectional specification: Fixed low power surface mount (SMD) resistors
EN 140401	Blank Detail Specification: Fixed low power non wire-wound surface mount (SMD) resistors
EN 140401-803	Detail specification: Fixed low power film SMD resistors - Cylindrical - Stability classes 0,05; 0,1; 0,25; 0,5; 1; 2

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